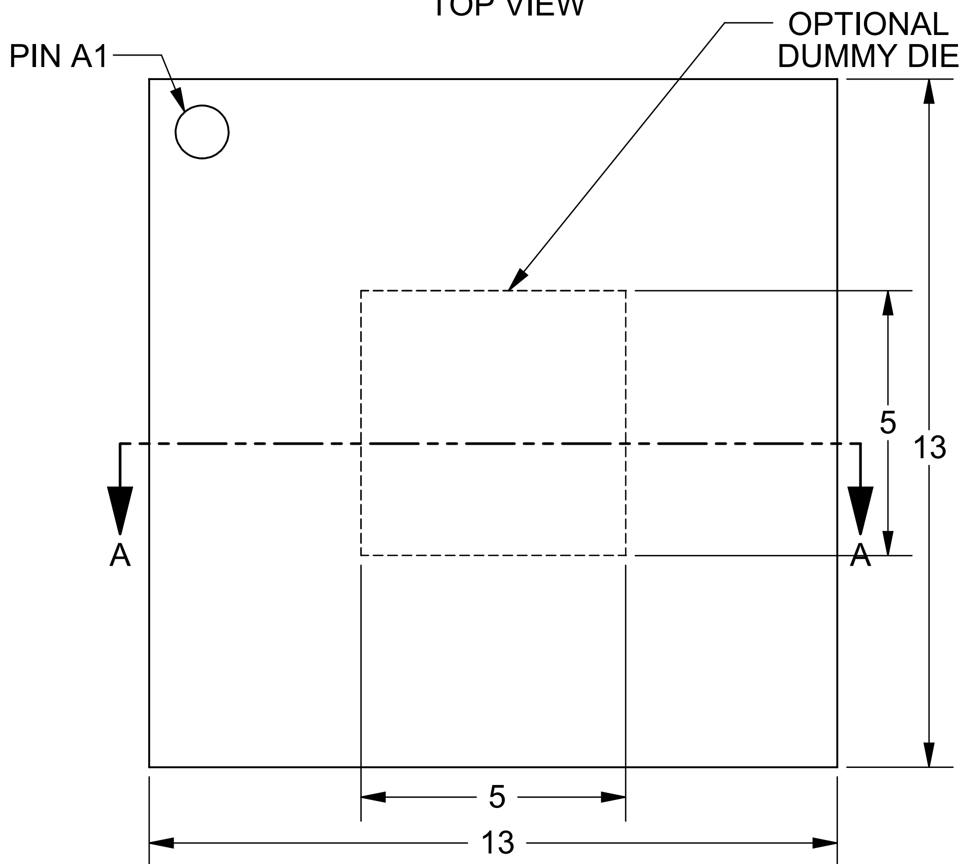
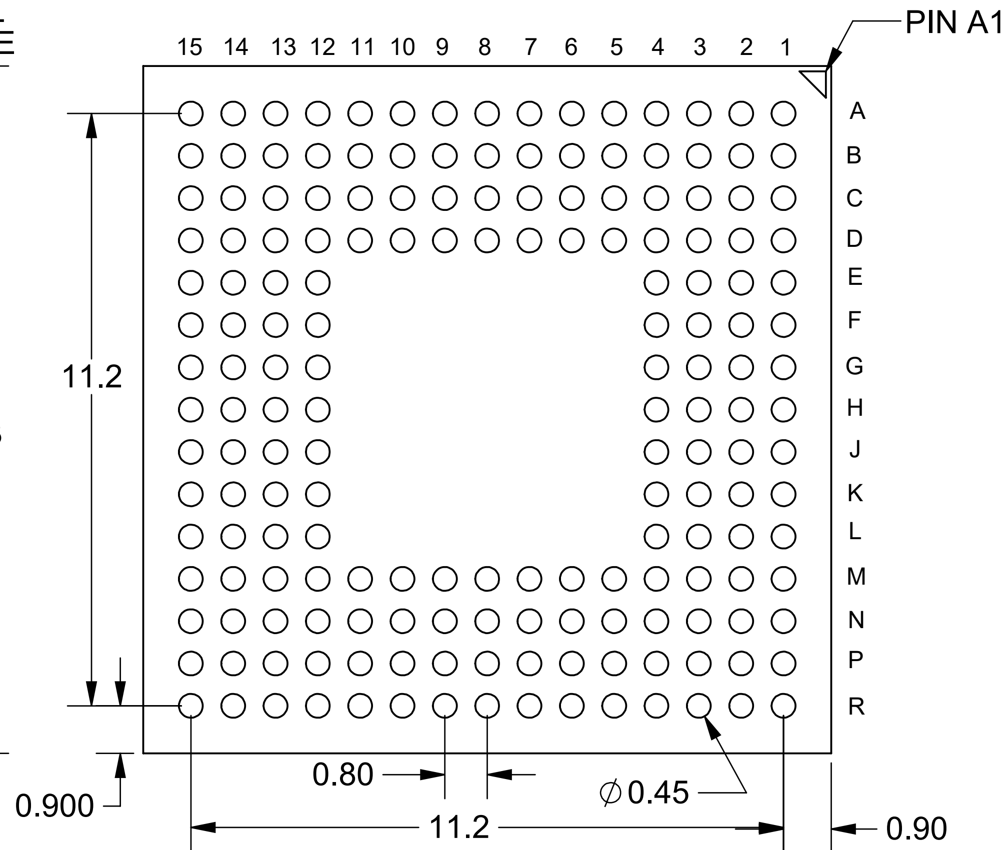
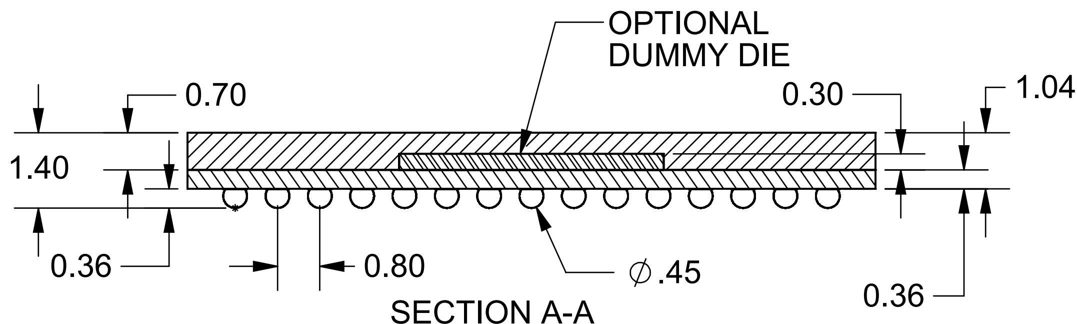




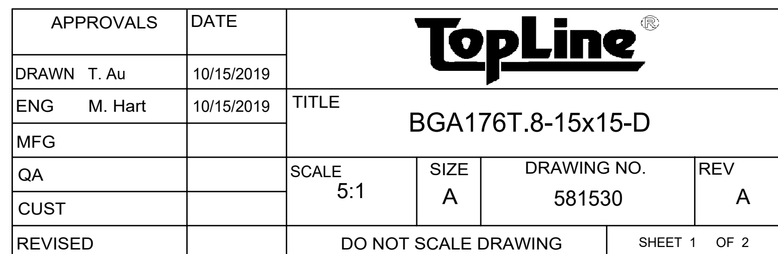


Notes: (Unless Otherwise Specified).

1) ALL DIMENSIONS ARE IN MM.
2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
3) BALL DIAMETER (BEFORE REFLOW): 0.45mm.
4) SOLDER MASK DEFINED PAD OPENING: 0.35mm.
5) PAD Cu DIAMETER: 0.457mm.
6) SUBSTRATE MATERIAL: BT (ALTERNATE FR4).
7) DUMMY DIE IS OPTIONAL.
8) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

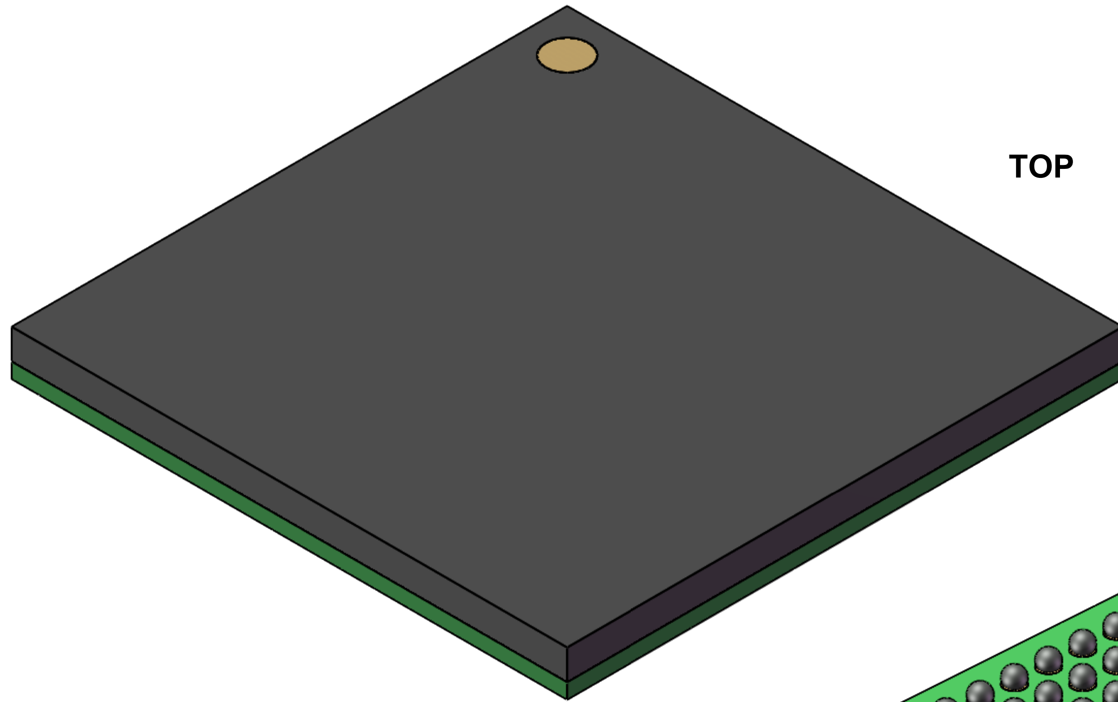
PART NUMBER TABLE

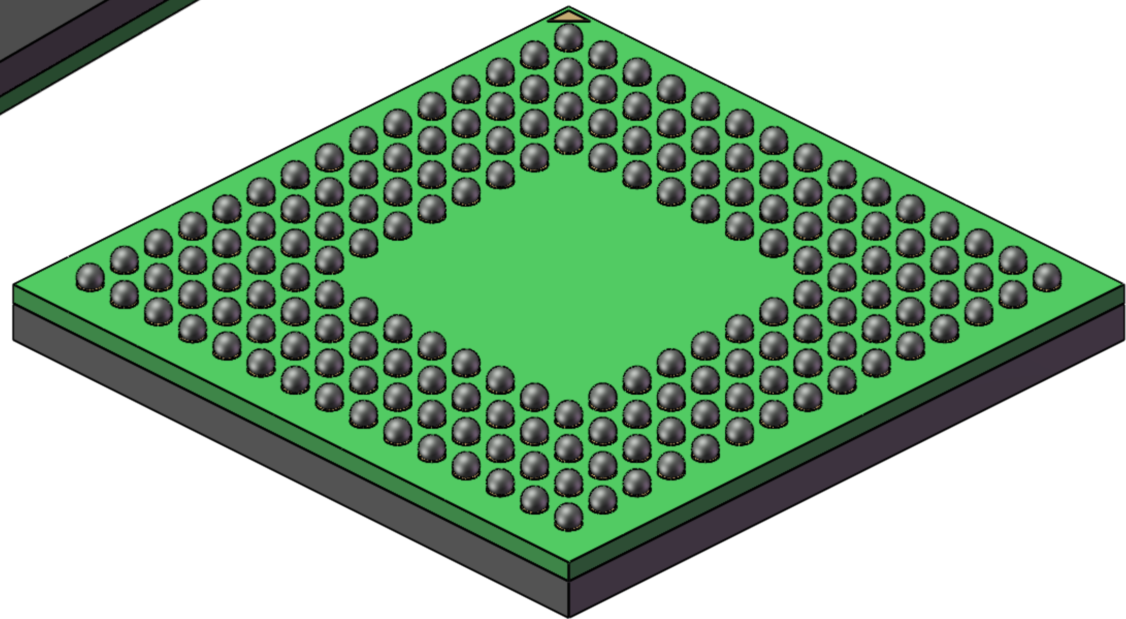
PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE
BGA176T.8C-15x15-D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA176T.8-15x15-D	Sn63/Pb37	NO	NO	YES



APPROVALS	DATE	
DRAWN T. Au	10/15/2019	TopLine®
ENG M. Hart	10/15/2019	TITLE BGA176T.8-15x15-D
MFG		
QA		SCALE 5:1 / SIZE A / DRAWING NO. 581530 / REV A
CUST		
REVISED		DO NOT SCALE DRAWING / SHEET 1 OF 2

MODEL





TopLine®			
TITLE BGA176T.8-15x15-D			
SCALE 5:1	SIZE A	DRAWING NO. 581530	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 2	